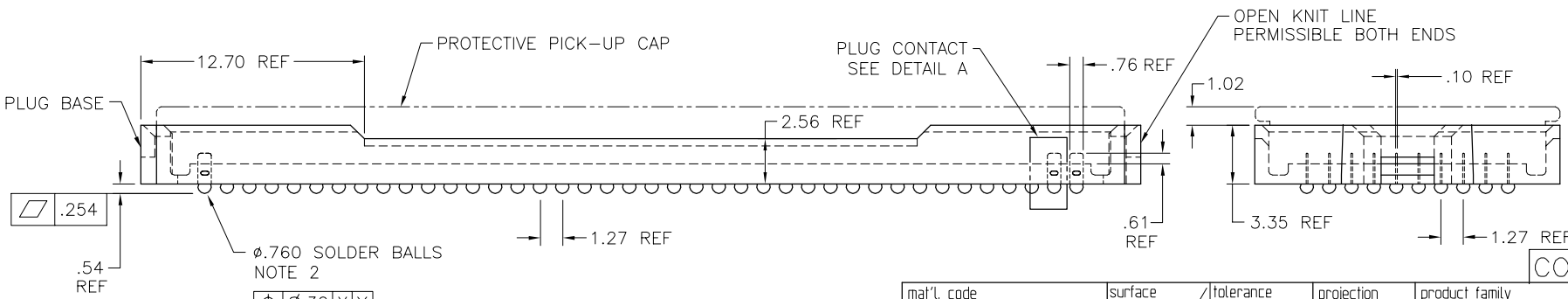
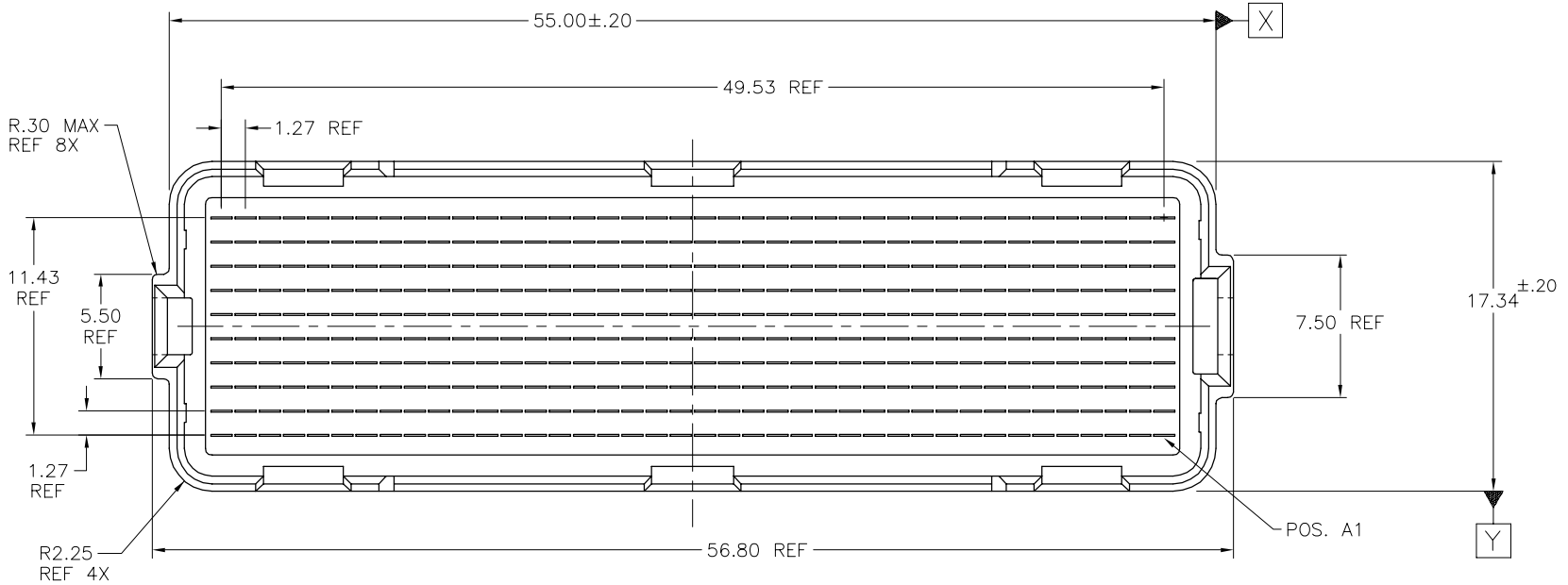


PRODUCT NUMBER
SEE TABLE

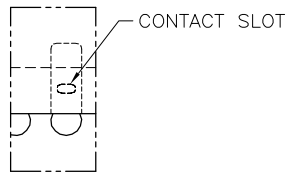


.254

.54 REF

Ø.760 SOLDER BALLS
NOTE 2

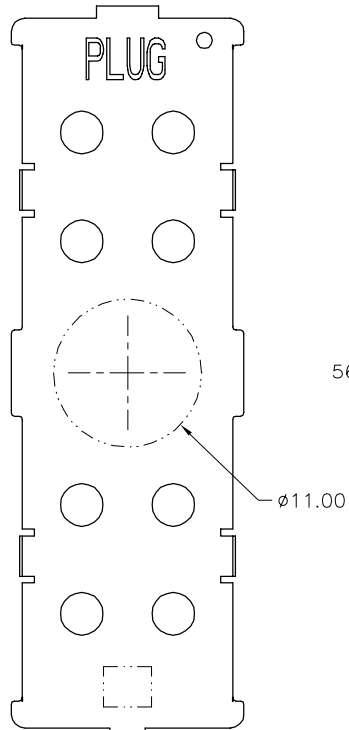
Ø.30 X Y



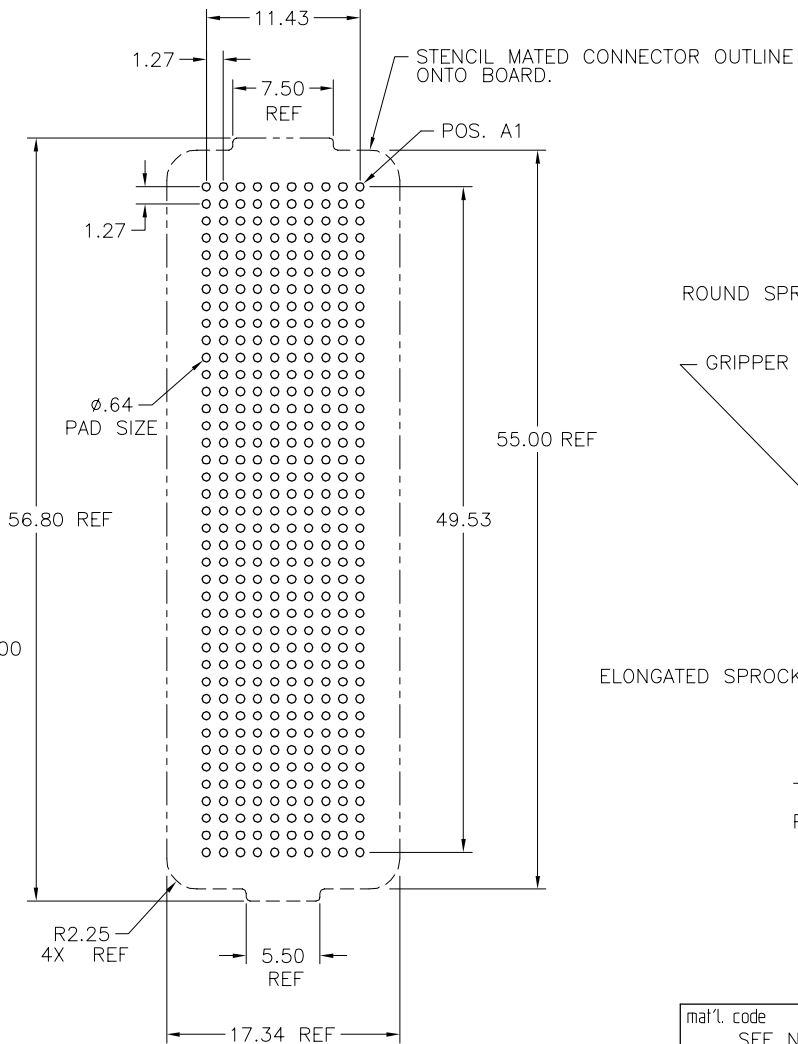
CONFIDENTIAL

mat'l. code SEE NOTE 1		surface ASME Y14.5	tolerance ASME Y14.5	projection 	product family MEG-ARRAY
tr		tolerances unless otherwise specified			title 0mm PLUG ASSY 10 x 40 = 400 POS.
A	v05-0324 DAI 04/19/05	angles	X #3		
B	v06-0560 LP 2006/07/18	linear	XX #13	scale 3:1	dwg no 10043857
C	v08-0084 LP 2008-03-18		80° ± 2'		
		dr	D.INGRAM 8/24/04		sheet 1 of 3 size A4
		engr	D.HARPER 8/24/04		
		chr	D.HARPER 8/24/04		
		appd	D.HARPER 8/24/04		
sheet index	revision sheet	C	C	C	type CUSTOMER Drawing
		1	2	3	

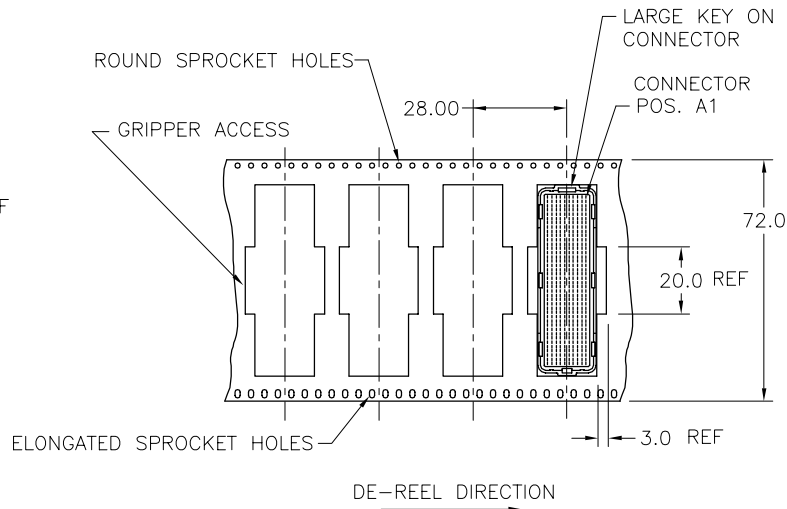
PRODUCT NUMBER
SEE TABLE



VACUUM AREA
FOR
PICK UP CAP



BOARD PATTERN
SCALE 2/1



TAPE & REEL PACKAGING SCALE NONE
PER EIA 481-3

CONFIDENTIAL

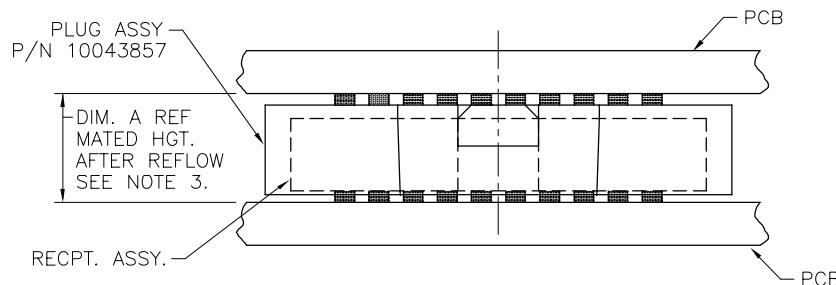
mat'l. code SEE NOTE 1		surface ASME Y14.5 ✓	tolerance ASME Y14.5	projection 	product family MEG-ARRAY
ltr	ecn no	dr	date	title 0mm PLUG ASSY. 10x40= 400 POS.	
c		tolerances unless otherwise specified		mm	
		angles	X ±3	scale 2:1	
		linear	.XX ±13	FCJ	
		0° ±2'	XXX ±051	dwg no 10043857	
		dr	D.INGRAM 8/24/04	sheet 2 of	
		engr	D.HARPER 8/24/04	size A4	
		chr	D.HARPER 8/24/04	type CUSTOMER Drawing	
		appd	D.HARPER 8/24/04		
sheet index	revision sheet				

PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
10043857-102	YES	30u"(0.76um) Au OVER Ni	SnPb
10043857-102LF			SnAgCu LEAD FREE (6)(7)
10043857-202	YES	SEE MATED HEIGHT TABLE (BELOW)	SnPb
10043857-202LF			SnAgCu LEAD FREE (6)(7)

NOTES:

- MAT'L:**
 HOUSING: LCP
 CONTACT: COPPER ALLOY

PLATING:
 CONTACT: (SEE TABLE ON SHEET3)
 SOLDER BALL: (SEE TABLE ON SHEET3)
 EUTECTIC SnPb OR LEAD FREE
 95.5Sn/4Ag/0.5Cu
- SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- PLATING FOR INDICATED -2XX SERIES PART NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).
- PLATING FOR INDICATED -2XX SERIES PART NOS. IS Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.
- FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION



MATED HEIGHT TABLE		
DIM. A	RECPT. ASSY. P/N	-2XX PLATING
4.0	74221	SEE NOTE 4
6.0	74388	SEE NOTE 5
8.0	74390	SEE NOTE 5

MATED HEIGHT AFTER REFLOW IS BASED ON ϕ .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE NONE

CONFIDENTIAL

mat'l. code SEE NOTE 1		surface ASME Y14.5 <input checked="" type="checkbox"/> ASME Y14.5	tolerance ASME Y14.5	projection 	product family MEG-ARRAY
ltr	ecn no	dr	date	title 0mm PLUG ASSY. 10x40= 400 POS.	
c				mm	
				scale 2:1	
		dr	D.INGRAM	8/24/04	dwg no 10043857
		engr	D.HARPER	8/24/04	sheet 3 of A4
		chr	D.HARPER	8/24/04	type CUSTOMER Drawing
		appd	D.HARPER	8/24/04	
sheet index	revision sheet				